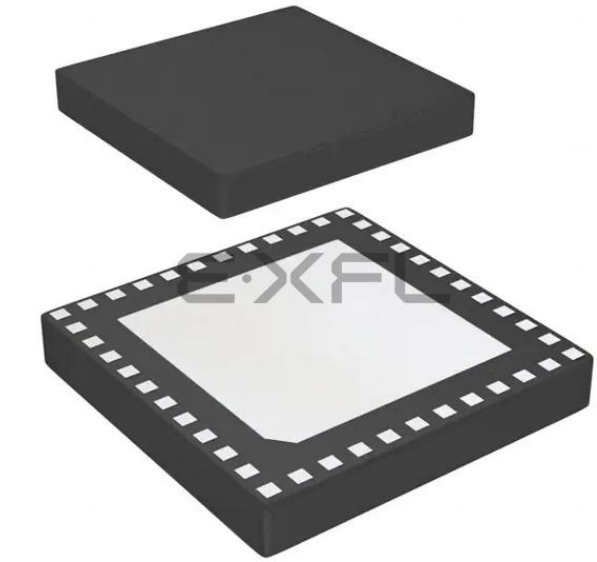

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	32KB (10.7K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VFTLA Exposed Pad
Supplier Device Package	44-VTLA (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep32mc204-i-tl

3.6 CPU Resources

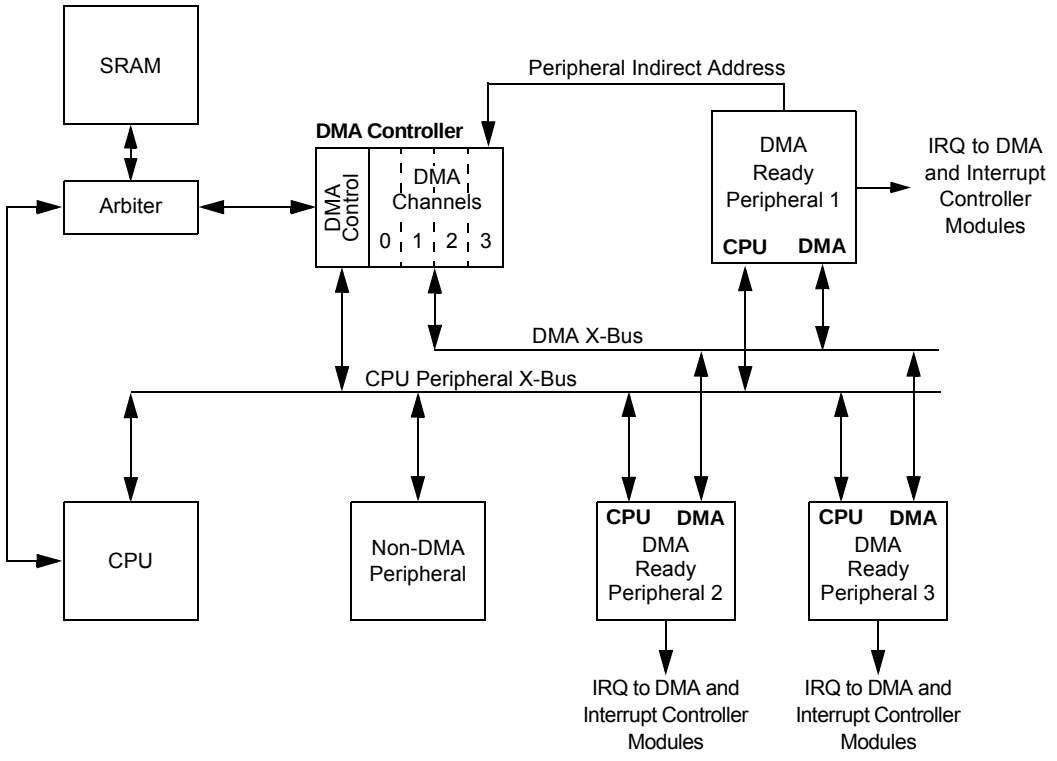
Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

3.6.1 KEY RESOURCES

- **"CPU"** (DS70359) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

FIGURE 8-2: DMA CONTROLLER BLOCK DIAGRAM



Note: CPU and DMA address buses are not shown for clarity.

8.1 DMA Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

8.1.1 KEY RESOURCES

- **Section 22. "Direct Memory Access (DMA)"** (DS70348) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

8.2 DMAC Registers

Each DMAC Channel x (where x = 0 through 3) contains the following registers:

- 16-Bit DMA Channel Control register (DMAxCON)
- 16-Bit DMA Channel IRQ Select register (DMAxREQ)
- 32-Bit DMA RAM Primary Start Address register (DMAxSTA)
- 32-Bit DMA RAM Secondary Start Address register (DMAxSTB)
- 16-Bit DMA Peripheral Address register (DMAxPAD)
- 14-Bit DMA Transfer Count register (DMAxCNT)

Additional status registers (DMAPWC, DMARQC, DMAPPS, DMALCA and DSADR) are common to all DMAC channels. These status registers provide information on write and request collisions, as well as on last address and channel access information.

The interrupt flags (DMAxIF) are located in an IFSx register in the interrupt controller. The corresponding interrupt enable control bits (DMAxIE) are located in an IECx register in the interrupt controller, and the corresponding interrupt priority control bits (DMAxIP) are located in an IPCx register in the interrupt controller.

REGISTER 9-2: CLKDIV: CLOCK DIVISOR REGISTER (CONTINUED)

bit 4-0 **PLLPRE<4:0>:** PLL Phase Detector Input Divider Select bits (also denoted as 'N1', PLL prescaler)
11111 = Input divided by 33
•
•
•
00001 = Input divided by 3
00000 = Input divided by 2 (default)

Note 1: The DOZE<2:0> bits can only be written to when the DOZEN bit is clear. If DOZEN = 1, any writes to DOZE<2:0> are ignored.

2: This bit is cleared when the ROI bit is set and an interrupt occurs.

3: The DOZEN bit cannot be set if DOZE<2:0> = 000. If DOZE<2:0> = 000, any attempt by user software to set the DOZEN bit is ignored.

REGISTER 10-5: PMD6: PERIPHERAL MODULE DISABLE CONTROL REGISTER 6

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	PWM3MD(1)	PWM2MD(1)	PWM1MD(1)
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-11 **Unimplemented:** Read as '0'

bit 10 **PWM3MD:** PWM3 Module Disable bit(1)
1 = PWM3 module is disabled
0 = PWM3 module is enabled

bit 9 **PWM2MD:** PWM2 Module Disable bit(1)
1 = PWM2 module is disabled
0 = PWM2 module is enabled

bit 8 **PWM1MD:** PWM1 Module Disable bit(1)
1 = PWM1 module is disabled
0 = PWM1 module is enabled

bit 7-0 **Unimplemented:** Read as '0'

Note 1: This bit is available on dsPIC33EPXXXMC50X/20X and PIC24EPXXXMC20X devices only.

REGISTER 11-9: RPINR15: PERIPHERAL PIN SELECT INPUT REGISTER 15 (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	HOME1R<6:0>						
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	INDX1R<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-8 **HOME1R<6:0>:** Assign QEI1 HOME1 (HOME1) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

bit 7 **Unimplemented:** Read as '0'

bit 6-0 **IND1XR<6:0>:** Assign QEI1 INDEX1 (INDX1) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

12.0 TIMER1

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Timers"** (DS70362) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Timer1 module is a 16-bit timer that can operate as a free-running interval timer/counter.

The Timer1 module has the following unique features over other timers:

- Can be operated in Asynchronous Counter mode from an external clock source
- The external clock input (T1CK) can optionally be synchronized to the internal device clock and the clock synchronization is performed after the prescaler

A block diagram of Timer1 is shown in Figure 12-1.

The Timer1 module can operate in one of the following modes:

- Timer mode
- Gated Timer mode
- Synchronous Counter mode
- Asynchronous Counter mode

In Timer and Gated Timer modes, the input clock is derived from the internal instruction cycle clock (FCY). In Synchronous and Asynchronous Counter modes, the input clock is derived from the external clock input at the T1CK pin.

The Timer modes are determined by the following bits:

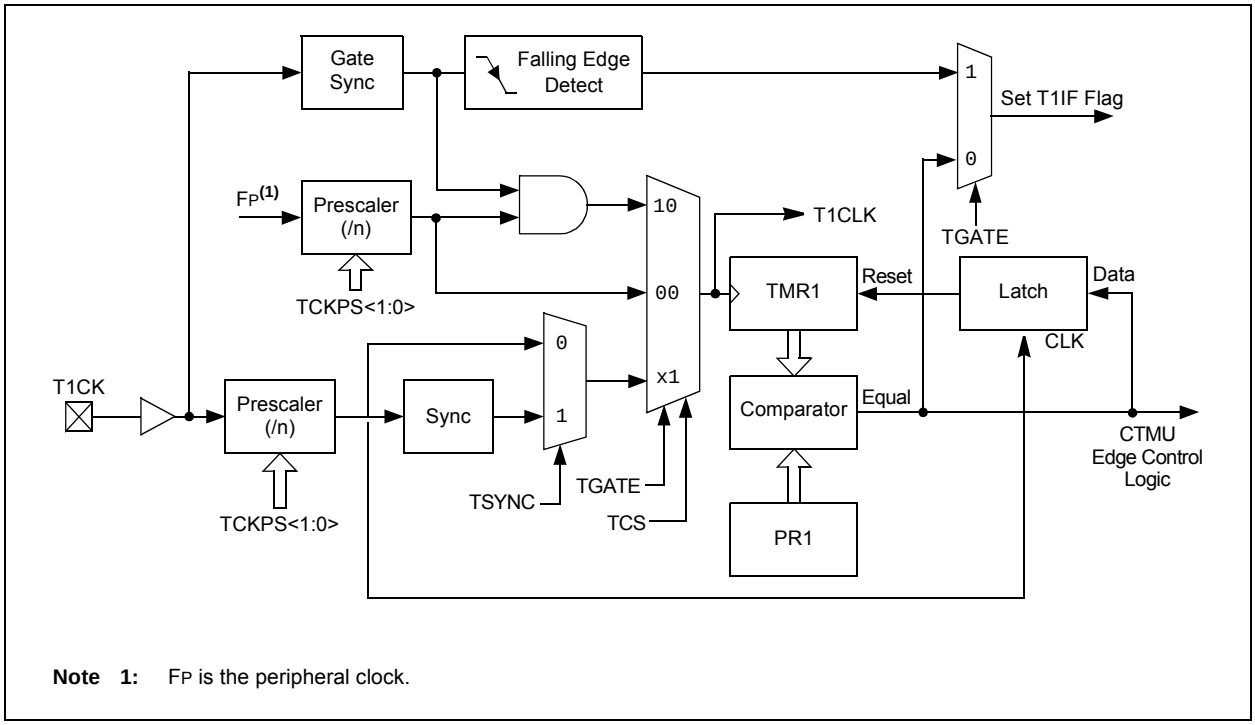
- Timer Clock Source Control bit (TCS): T1CON<1>
- Timer Synchronization Control bit (TSYNC): T1CON<2>
- Timer Gate Control bit (TGATE): T1CON<6>

Timer control bit setting for different operating modes are given in the Table 12-1.

TABLE 12-1: TIMER MODE SETTINGS

Mode	TCS	TGATE	TSYNC
Timer	0	0	x
Gated Timer	0	1	x
Synchronous Counter	1	x	1
Asynchronous Counter	1	x	0

FIGURE 12-1: 16-BIT TIMER1 MODULE BLOCK DIAGRAM



Note 1: FP is the peripheral clock.

NOTES:

16.2 PWM Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

16.2.1 KEY RESOURCES

- **"High-Speed PWM"** (DS70645) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

REGISTER 21-19: CxFMSKSEL2: ECANx FILTER 15-8 MASK SELECTION REGISTER 2

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F15MSK<1:0>		F14MSK<1:0>		F13MSK<1:0>		F12MSK<1:0>	
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F11MSK<1:0>		F10MSK<1:0>		F9MSK<1:0>		F8MSK<1:0>	
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **F15MSK<1:0>:** Mask Source for Filter 15 bits
11 = Reserved
10 = Acceptance Mask 2 registers contain mask
01 = Acceptance Mask 1 registers contain mask
00 = Acceptance Mask 0 registers contain mask

bit 13-12 **F14MSK<1:0>:** Mask Source for Filter 14 bits (same values as bits<15:14>)

bit 11-10 **F13MSK<1:0>:** Mask Source for Filter 13 bits (same values as bits<15:14>)

bit 9-8 **F12MSK<1:0>:** Mask Source for Filter 12 bits (same values as bits<15:14>)

bit 7-6 **F11MSK<1:0>:** Mask Source for Filter 11 bits (same values as bits<15:14>)

bit 5-4 **F10MSK<1:0>:** Mask Source for Filter 10 bits (same values as bits<15:14>)

bit 3-2 **F9MSK<1:0>:** Mask Source for Filter 9 bits (same values as bits<15:14>)

bit 1-0 **F8MSK<1:0>:** Mask Source for Filter 8 bits (same values as bits<15:14>)

21.5 ECAN Message Buffers

ECAN Message Buffers are part of RAM memory. They are not ECAN Special Function Registers. The user application must directly write into the RAM area that is configured for ECAN Message Buffers. The location and size of the buffer area is defined by the user application.

BUFFER 21-1: ECAN™ MESSAGE BUFFER WORD 0

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	SID10	SID9	SID8	SID7	SID6
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SID5	SID4	SID3	SID2	SID1	SID0	SRR	IDE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12-2 **SID<10:0>:** Standard Identifier bits

bit 1 **SRR:** Substitute Remote Request bit
When IDE = 0:
1 = Message will request remote transmission
0 = Normal message
When IDE = 1:
The SRR bit must be set to '1'.

bit 0 **IDE:** Extended Identifier bit
1 = Message will transmit Extended Identifier
0 = Message will transmit Standard Identifier

BUFFER 21-2: ECAN™ MESSAGE BUFFER WORD 1

U-0	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	—	EID17	EID16	EID15	EID14
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
EID13	EID12	EID11	EID10	EID9	EID8	EID7	EID6
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-12 **Unimplemented:** Read as '0'

bit 11-0 **EID<17:6>:** Extended Identifier bits

REGISTER 23-5: AD1CHS123: ADC1 INPUT CHANNEL 1, 2, 3 SELECT REGISTER (CONTINUED)

bit 0 **CH123SA:** Channel 1, 2, 3 Positive Input Select for Sample MUXA bit

In 12-bit mode (AD21B = 1), CH123SA is Unimplemented and is Read as '0':

Value	ADC Channel		
	CH1	CH2	CH3
1(2)	OA1/AN3	OA2/AN0	OA3/AN6
0(1,2)	OA2/AN0	AN1	AN2

Note 1: AN0 through AN7 are repurposed when comparator and op amp functionality is enabled. See Figure 23-1 to determine how enabling a particular op amp or comparator affects selection choices for Channels 1, 2 and 3.

2: The OAx input is used if the corresponding op amp is selected (OPMODE (CMxCON<10>) = 1); otherwise, the ANx input is used.

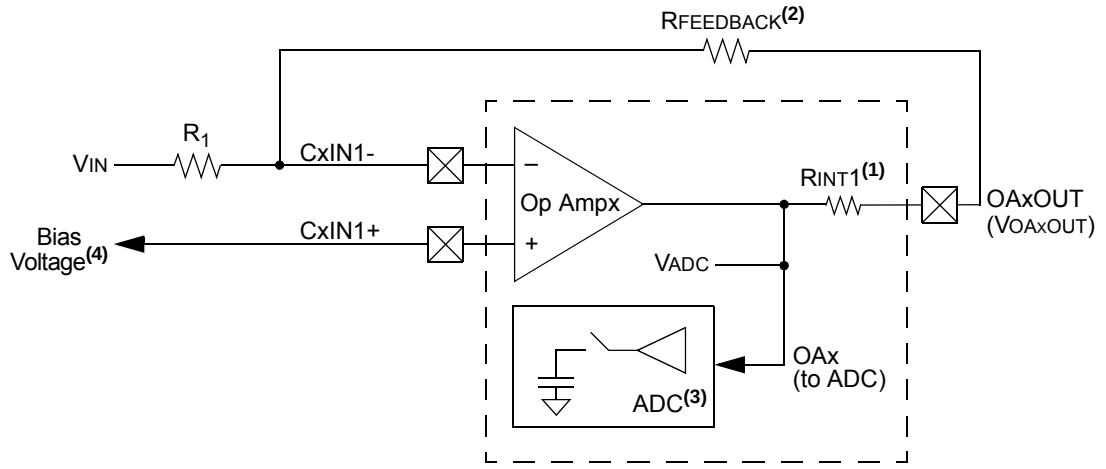
25.1 Op Amp Application Considerations

There are two configurations to take into consideration when designing with the op amp modules that are available in the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices. Configuration A (see Figure 25-6) takes advantage of the internal connection to the ADC module to route the output of the op amp directly to the ADC for measurement. Configuration B (see Figure 25-7) requires that the designer externally route the output of the op amp (OAxOUT) to a separate analog input pin (ANy) on the device. Table 30-55 in **Section 30.0 "Electrical Characteristics"** describes the performance characteristics for the op amps, distinguishing between the two configuration types where applicable.

25.1.1 OP AMP CONFIGURATION A

Figure 25-6 shows a typical inverting amplifier circuit taking advantage of the internal connections from the op amp output to the input of the ADC. The advantage of this configuration is that the user does not need to consume another analog input (ANy) on the device, and allows the user to simultaneously sample all three op amps with the ADC module, if needed. However, the presence of the internal resistance, RINT1, adds an error in the feedback path. Since RINT1 is an internal resistance, in relation to the op amp output (VOAXOUT) and ADC internal connection (VADC), RINT1 must be included in the numerator term of the transfer function. See Table 30-53 in **Section 30.0 "Electrical Characteristics"** for the typical value of RINT1. Table 30-60 and Table 30-61 in **Section 30.0 "Electrical Characteristics"** describe the minimum sample time (TSAMP) requirements for the ADC module in this configuration. Figure 25-6 also defines the equations that should be used when calculating the expected voltages at points, VADC and VOAXOUT.

FIGURE 25-6: OP AMP CONFIGURATION A



$$V_{ADC} = \left(\frac{R_{FEEDBACK} + R_{INT1}}{R_1}\right)(\ Bias\ Voltage - V_{IN} \ )$$

$$V_{OAxOUT} = \left(\frac{R_{FEEDBACK}}{R_1}\right)(\ Bias\ Voltage - V_{IN} \ )$$

Note 1: See Table 30-53 for the Typical value.
2: See Table 30-53 for the Minimum value for the feedback resistor.
3: See Table 30-60 and Table 30-61 for the minimum sample time (TSAMP).
4: CVREF1O or CVREF2O are two options that are available for supplying bias voltage to the op amps.

27.5 Watchdog Timer (WDT)

For dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices, the WDT is driven by the LPRC oscillator. When the WDT is enabled, the clock source is also enabled.

27.5.1 PRESCALER/POSTSCALER

The nominal WDT clock source from LPRC is 32 kHz. This feeds a prescaler that can be configured for either 5-bit (divide-by-32) or 7-bit (divide-by-128) operation. The prescaler is set by the WDTPRE Configuration bit. With a 32 kHz input, the prescaler yields a WDT Time-out period (TWDT), as shown in Parameter SY12 in Table 30-22.

A variable postscaler divides down the WDT prescaler output and allows for a wide range of time-out periods. The postscaler is controlled by the WDTPOST<3:0> Configuration bits (FWDT<3:0>), which allow the selection of 16 settings, from 1:1 to 1:32,768. Using the prescaler and postscaler, time-out periods ranging from 1 ms to 131 seconds can be achieved.

The WDT, prescaler and postscaler are reset:

- On any device Reset
- On the completion of a clock switch, whether invoked by software (i.e., setting the OSWEN bit after changing the NOSCx bits) or by hardware (i.e., Fail-Safe Clock Monitor)
- When a PWRSAV instruction is executed (i.e., Sleep or Idle mode is entered)
- When the device exits Sleep or Idle mode to resume normal operation
- By a CLRWDT instruction during normal execution

Note: The CLRWDT and PWRSAV instructions clear the prescaler and postscaler counts when executed.

27.5.2 SLEEP AND IDLE MODES

If the WDT is enabled, it continues to run during Sleep or Idle modes. When the WDT time-out occurs, the device wakes the device and code execution continues from where the PWRSAV instruction was executed. The corresponding SLEEP or IDLE bit (RCON<3,2>) needs to be cleared in software after the device wakes up.

27.5.3 ENABLING WDT

The WDT is enabled or disabled by the FWDTEN Configuration bit in the FWDT Configuration register. When the FWDTEN Configuration bit is set, the WDT is always enabled.

The WDT can be optionally controlled in software when the FWDTEN Configuration bit has been programmed to '0'. The WDT is enabled in software by setting the SWDTEN control bit (RCON<5>). The SWDTEN control bit is cleared on any device Reset. The software WDT option allows the user application to enable the WDT for critical code segments and disable the WDT during non-critical segments for maximum power savings.

The WDT flag bit, WDTO (RCON<4>), is not automatically cleared following a WDT time-out. To detect subsequent WDT events, the flag must be cleared in software.

27.5.4 WDT WINDOW

The Watchdog Timer has an optional Windowed mode, enabled by programming the WINDIS bit in the WDT Configuration register (FWDT<6>). In the Windowed mode (WINDIS = 0), the WDT should be cleared based on the settings in the programmable Watchdog Timer Window select bits (WDTWIN<1:0>).

FIGURE 27-2: WDT BLOCK DIAGRAM

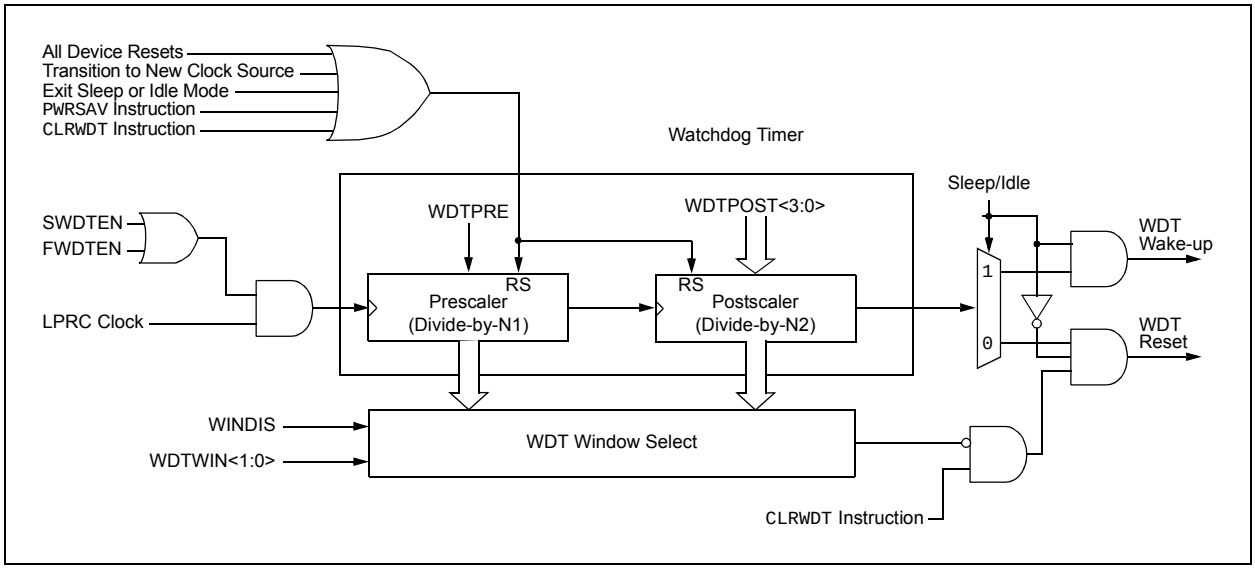


TABLE 30-9: DC CHARACTERISTICS: WATCHDOG TIMER DELTA CURRENT (ΔI_{WDT})(1)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended		
Parameter No.	**Typ.**	**Max.**	**Units**	**Conditions**	
DC61d	8	—	μA	-40°C	3.3V
DC61a	10	—	μA	+25°C	
DC61b	12	—	μA	+85°C	
DC61c	13	—	μA	+125°C	

Note 1: The ΔI_{WDT} current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current. All parameters are characterized but not tested during manufacturing.

TABLE 30-10: DC CHARACTERISTICS: DOZE CURRENT (I_{DOZE})

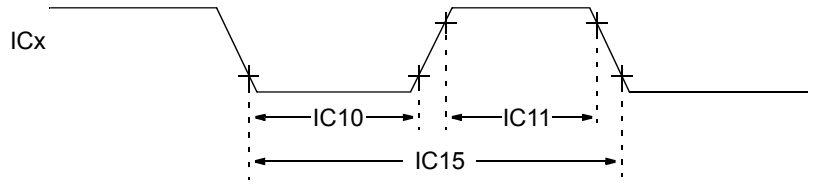
DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Parameter No.	**Typ.**	**Max.**	**Doze Ratio**	**Units**	**Conditions**		
Doze Current (I_{DOZE})(1)							
DC73a(2)	35	—	1:2	mA	-40°C	3.3V	FOSC = 140 MHz
DC73g	20	30	1:128	mA			
DC70a(2)	35	—	1:2	mA	+25°C	3.3V	FOSC = 140 MHz
DC70g	20	30	1:128	mA			
DC71a(2)	35	—	1:2	mA	+85°C	3.3V	FOSC = 140 MHz
DC71g	20	30	1:128	mA			
DC72a(2)	28	—	1:2	mA	+125°C	3.3V	FOSC = 120 MHz
DC72g	15	30	1:128	mA			

Note 1: I_{DOZE} is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all I_{DOZE} measurements are as follows:

- Oscillator is configured in EC mode and external clock is active, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{MCLR}$ = VDD, WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating; however, every peripheral is being clocked (all PMDx bits are zeroed)
- CPU is executing `while(1)` statement
- JTAG is disabled

2: Parameter is characterized but not tested in manufacturing.

FIGURE 30-6: INPUT CAPTURE x (ICx) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-26: INPUT CAPTURE x MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Max.**	**Units**	**Conditions**	
IC10	TccL	ICx Input Low Time	Greater of 12.5 + 25 or (0.5 TCY/N) + 25	—	ns	Must also meet Parameter IC15	N = prescale value (1, 4, 16)
IC11	TccH	ICx Input High Time	Greater of 12.5 + 25 or (0.5 TCY/N) + 25	—	ns	Must also meet Parameter IC15	
IC15	TccP	ICx Input Period	Greater of 25 + 50 or (1 TCY/N) + 50	—	ns		

Note 1: These parameters are characterized, but not tested in manufacturing.

FIGURE 30-32: I2Cx BUS START/STOP BITS TIMING CHARACTERISTICS (SLAVE MODE)

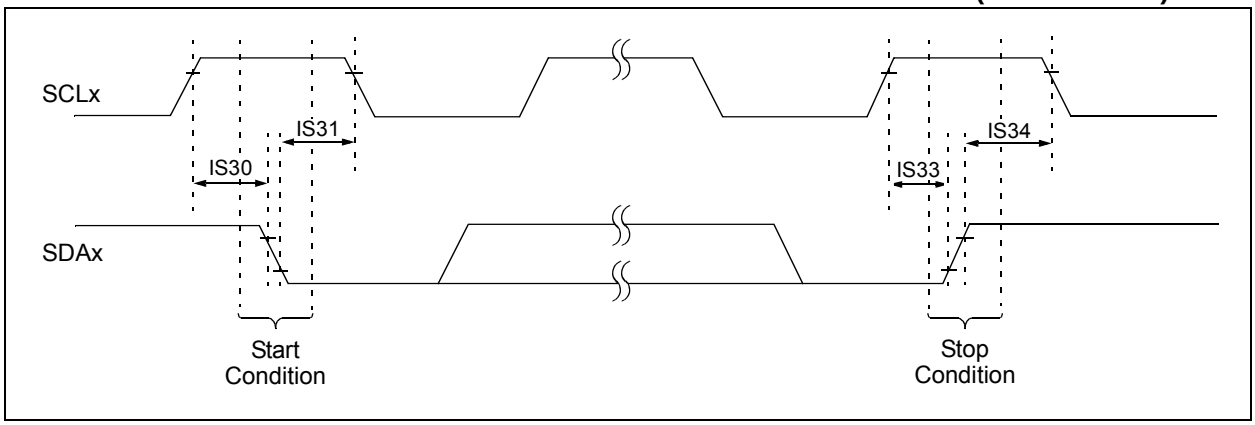
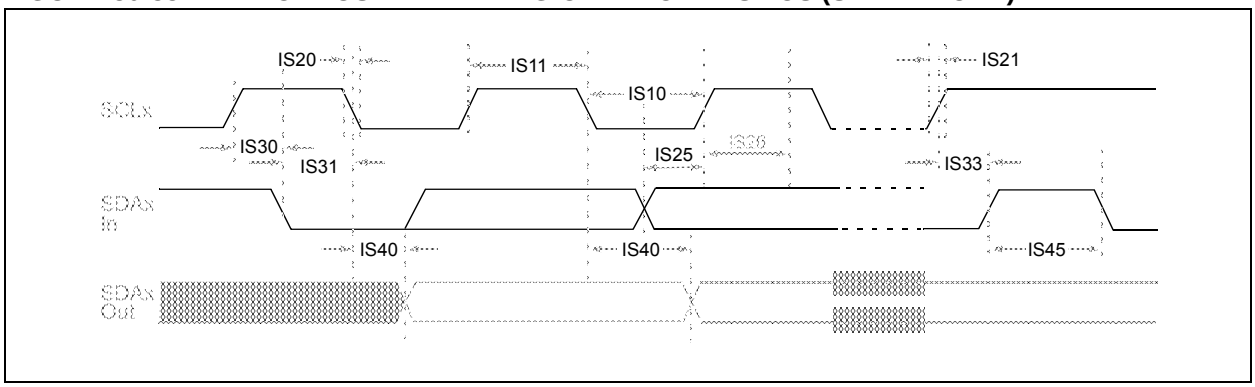
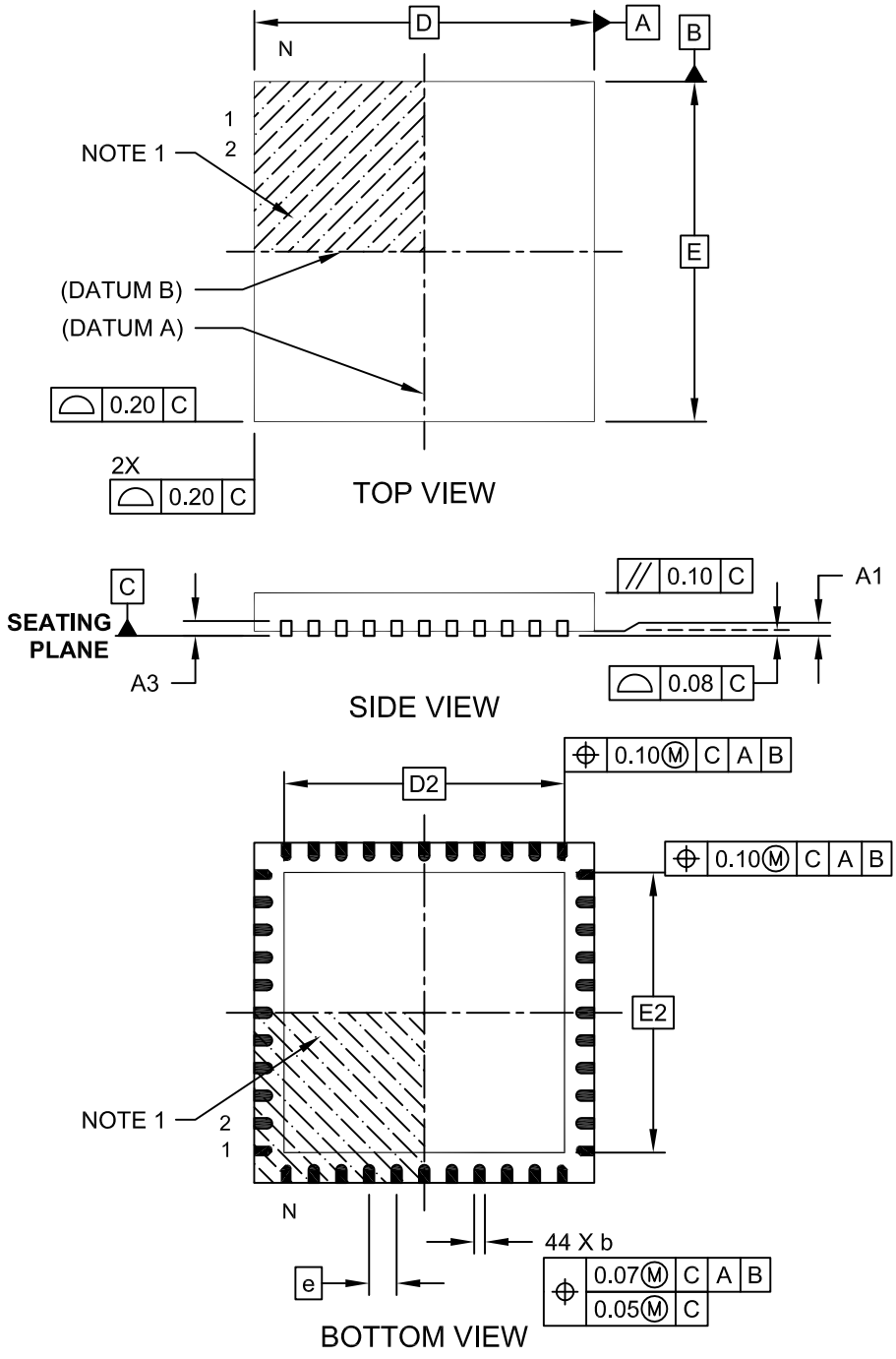


FIGURE 30-33: I2Cx BUS DATA TIMING CHARACTERISTICS (SLAVE MODE)



44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

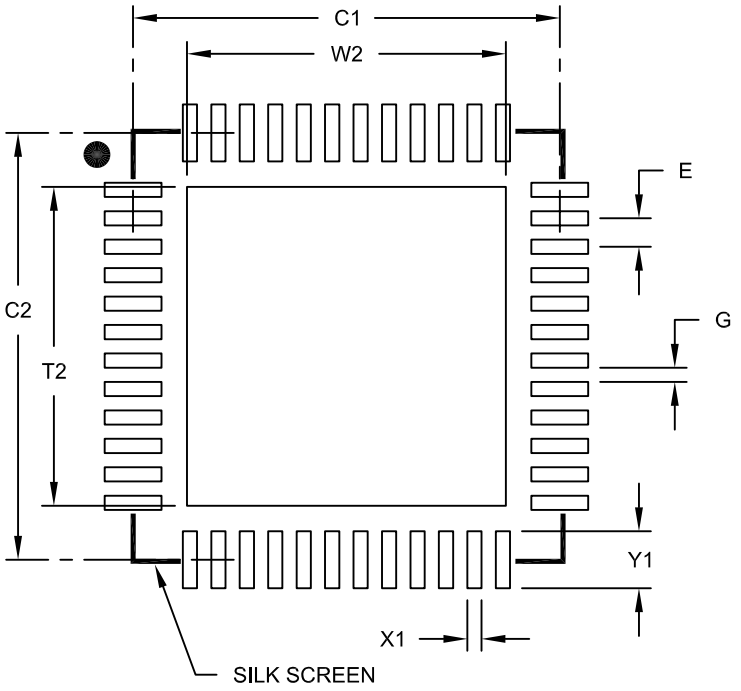
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-103C Sheet 1 of 2

48-Lead Ultra Thin Plastic Quad Flat, No Lead Package (MV) - 6x6 mm Body [UQFN]
With 0.40 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.40 BSC	
Optional Center Pad Width	W2			4.45
Optional Center Pad Length	T2			4.45
Contact Pad Spacing	C1		6.00	
Contact Pad Spacing	C2		6.00	
Contact Pad Width (X28)	X1			0.20
Contact Pad Length (X28)	Y1			0.80
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2153A

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- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
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